

FIG.1

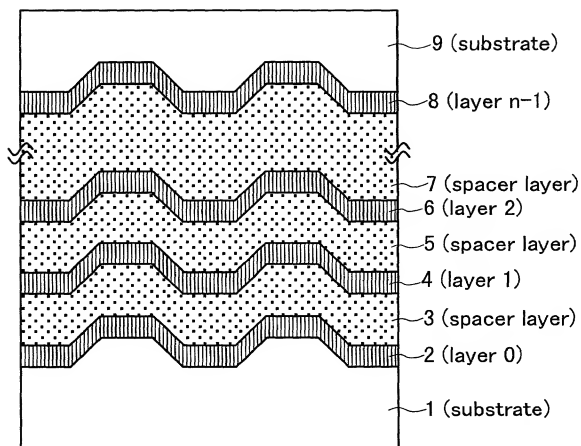


FIG.2

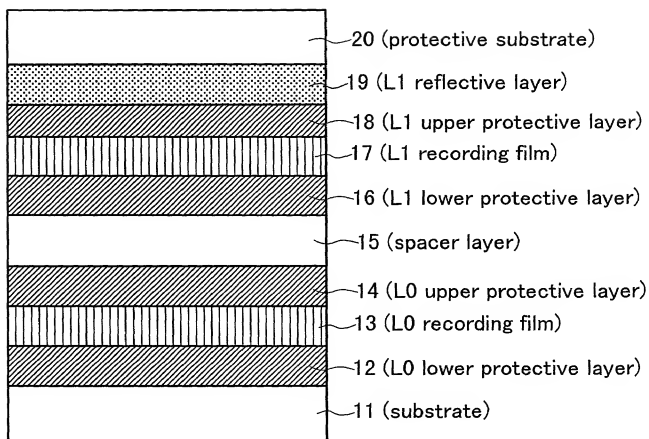


FIG.3

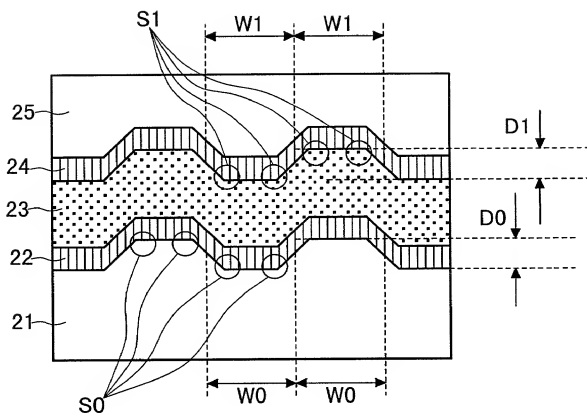
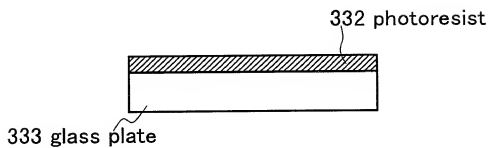
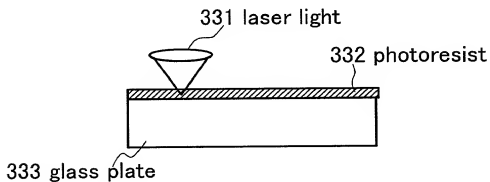


FIG.4

step 1 (spreading out photoresist)



step 2 (exposure)



step 3 (development)

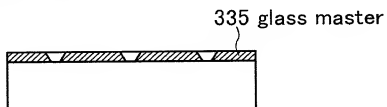
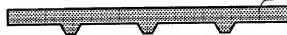


FIG.5

step 4 (stamper)

336 nickel stamper for
injection of substrate



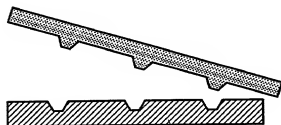
step 5 (injection)



337 substrate



step 6 (remove)



337 substrate

FIG.6

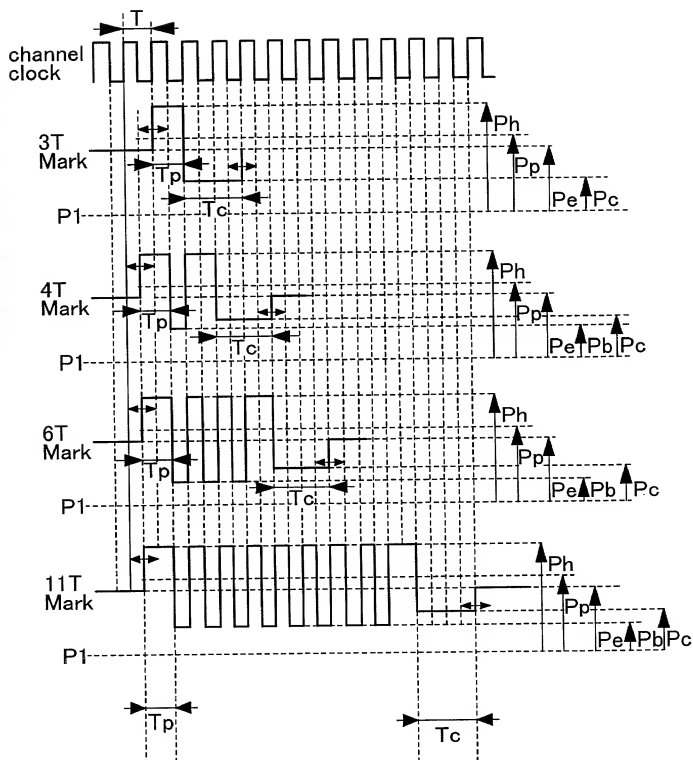


FIG.7

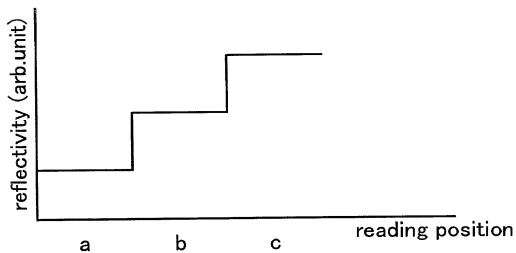
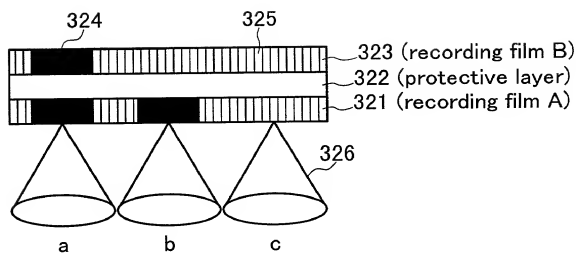


FIG.8

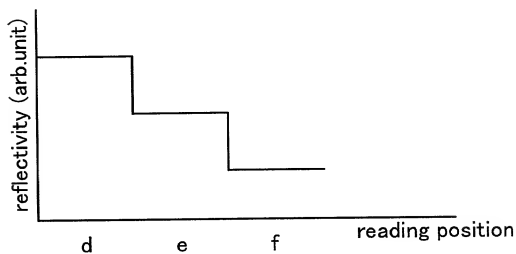
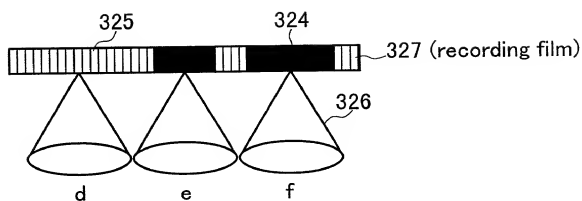


FIG.10

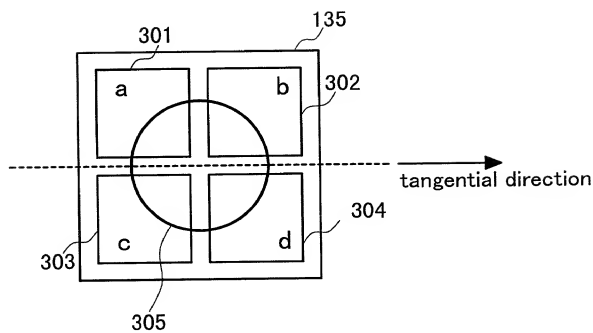


FIG.11

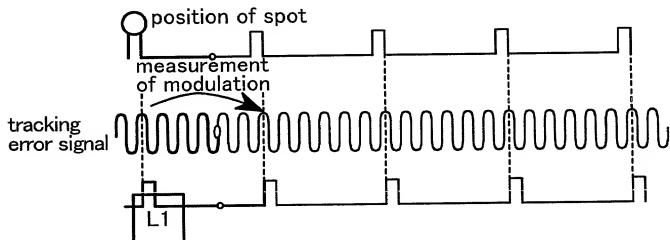
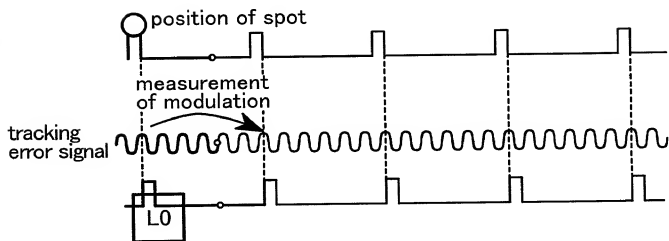
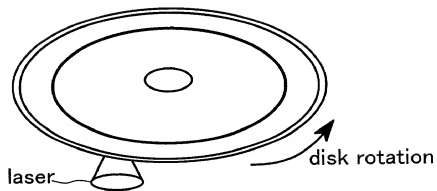


FIG.12

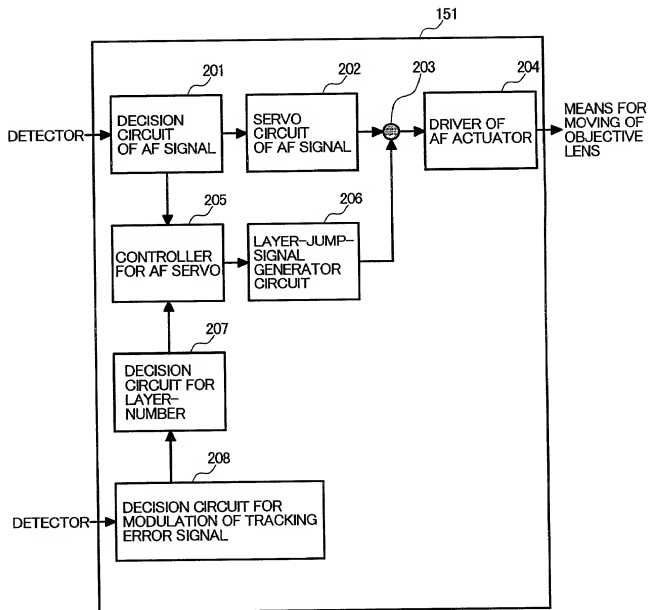


FIG.13

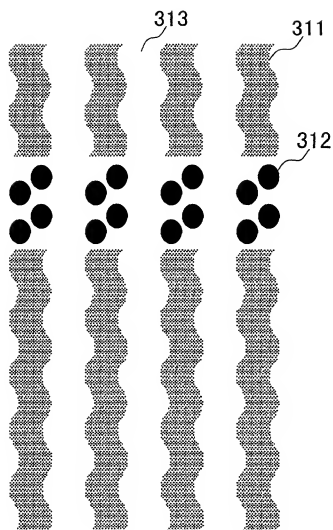


FIG. 14

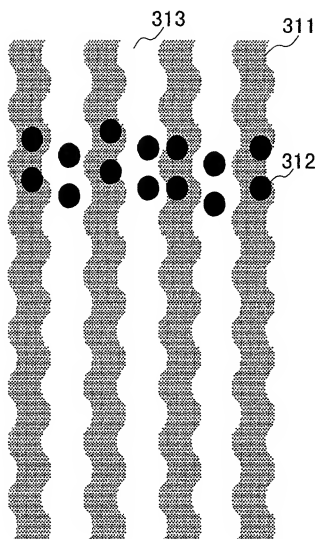


FIG.15

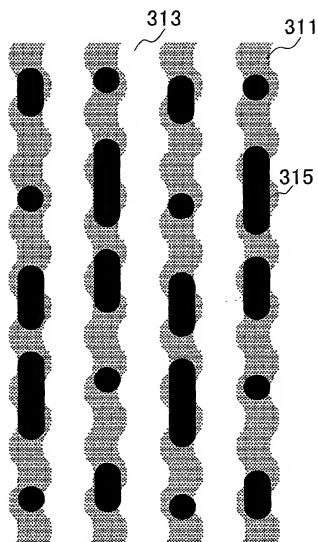


FIG.16

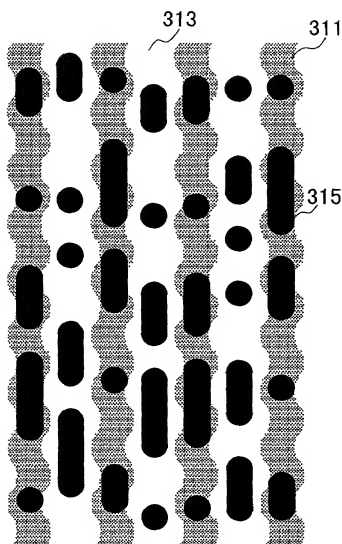


FIG.17

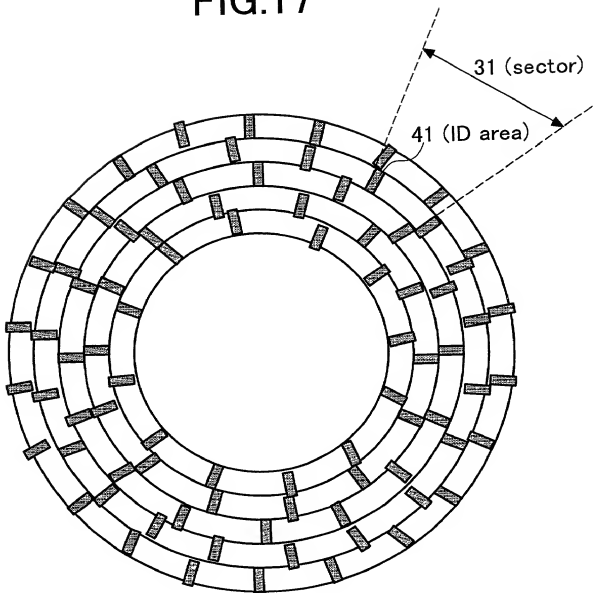


FIG.18

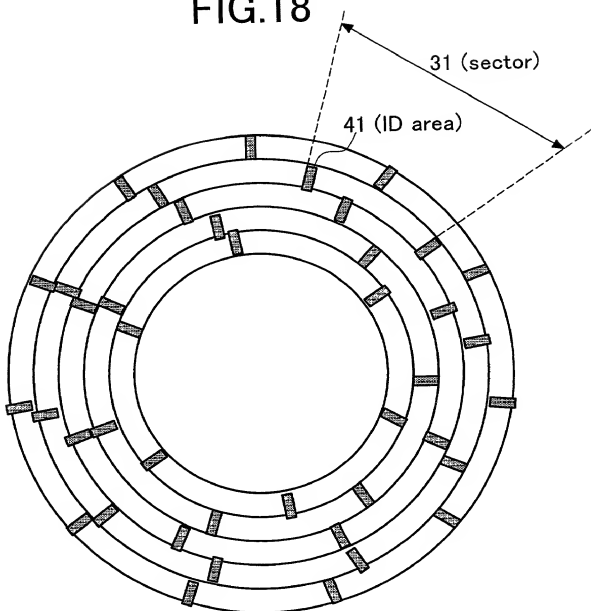


FIG.19

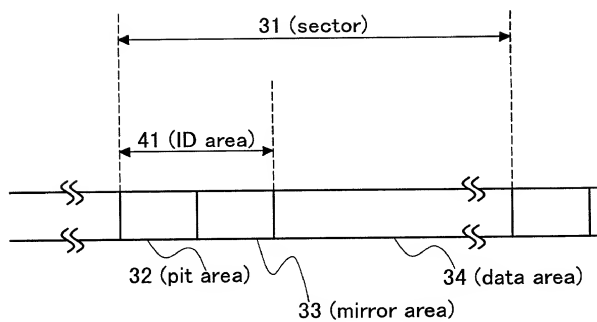


FIG.20

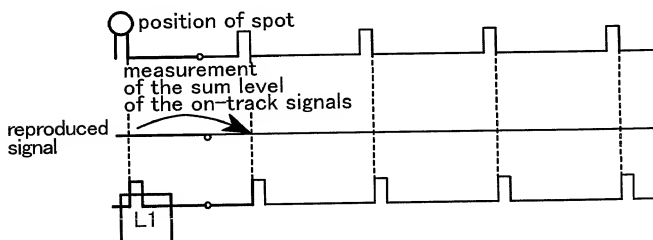
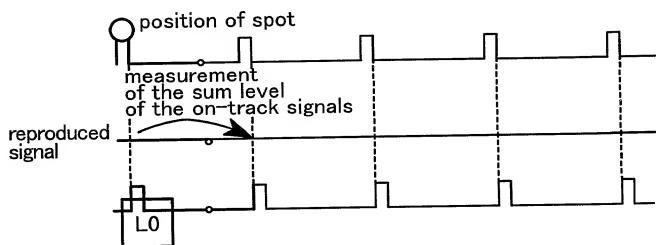
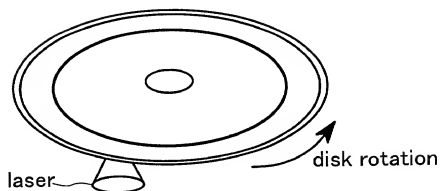
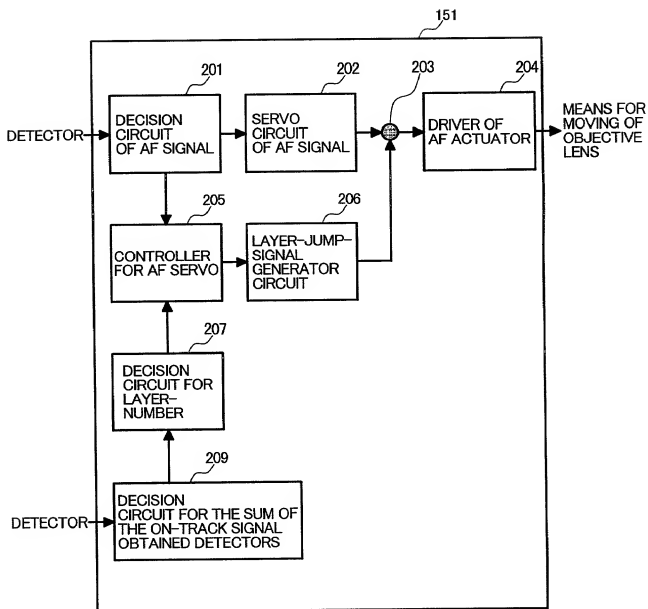


FIG.21



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FIG.22

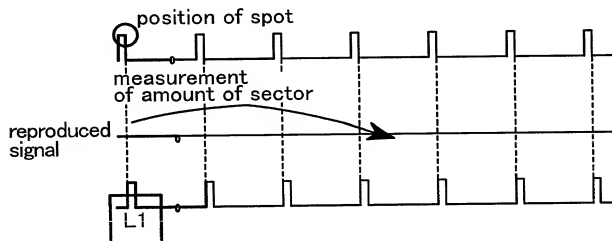
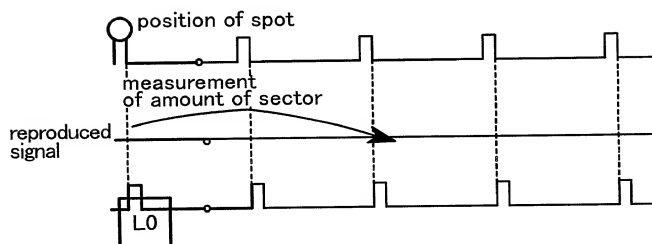
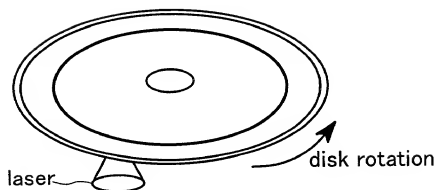


FIG.23

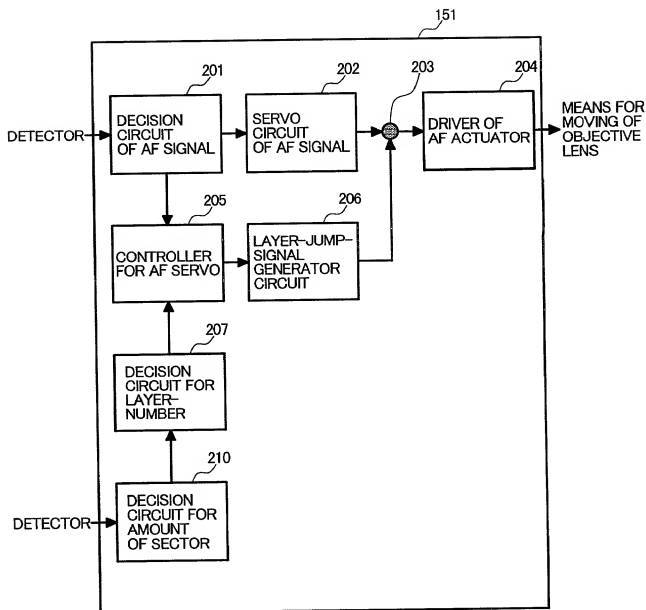


FIG.24

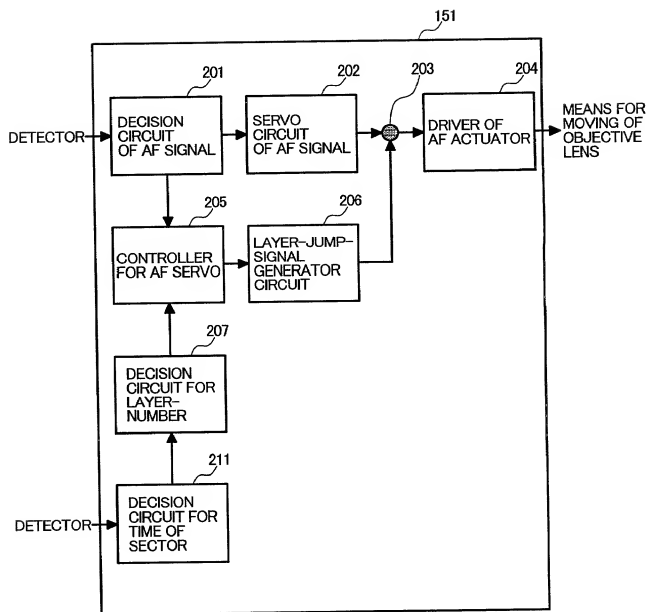


FIG.25

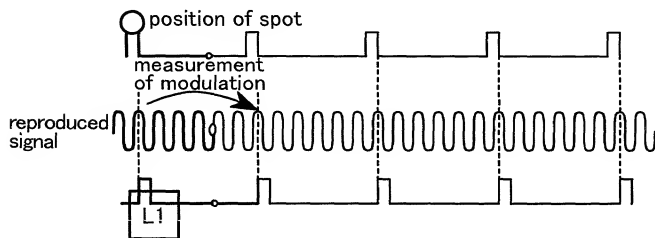
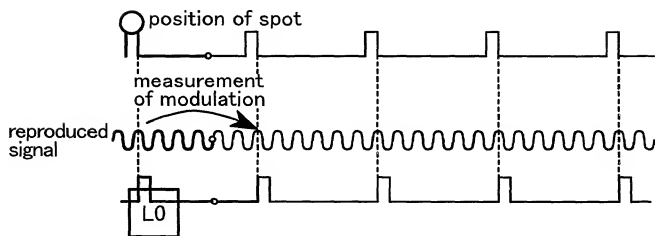
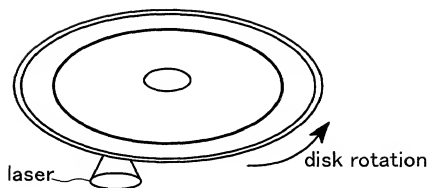


FIG.26

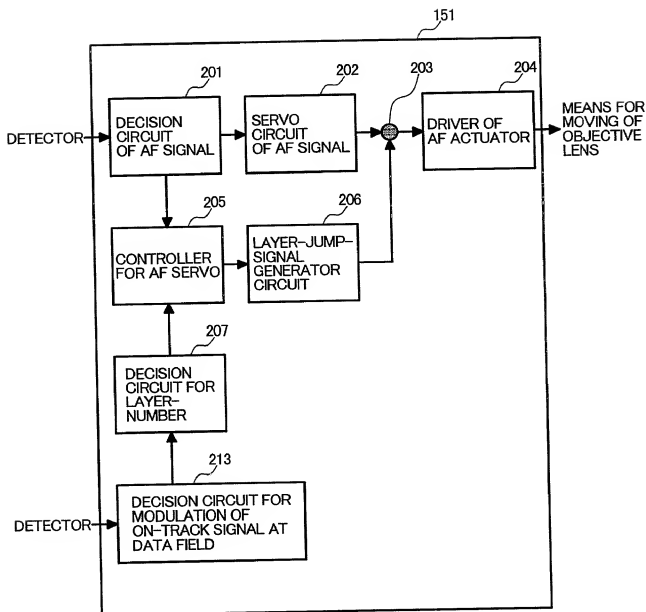


FIG.27

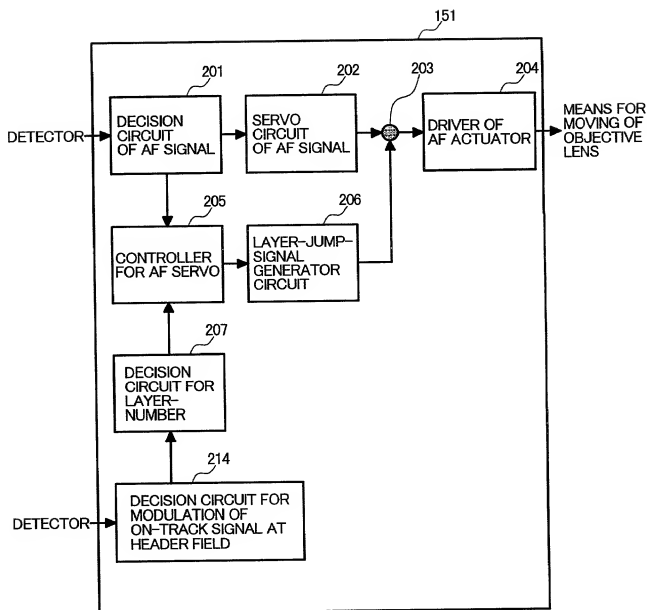
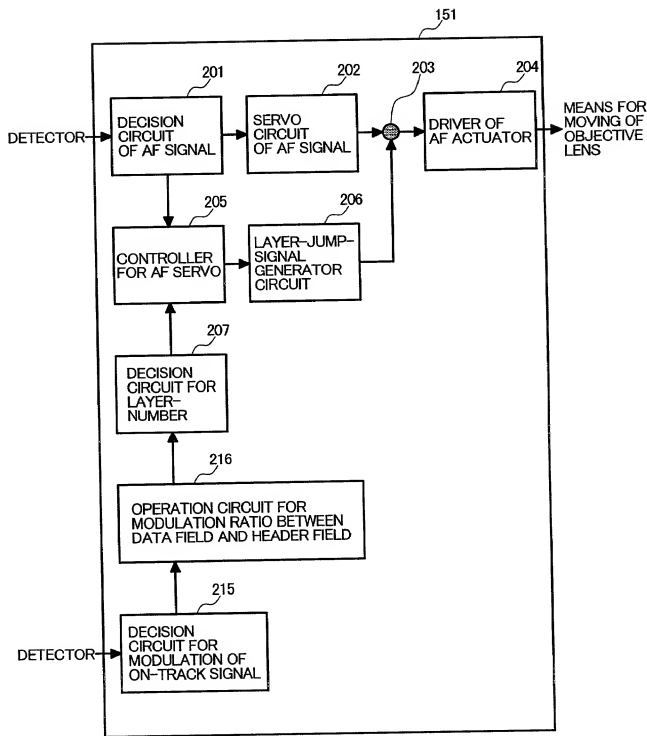


FIG.28



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FIG.29

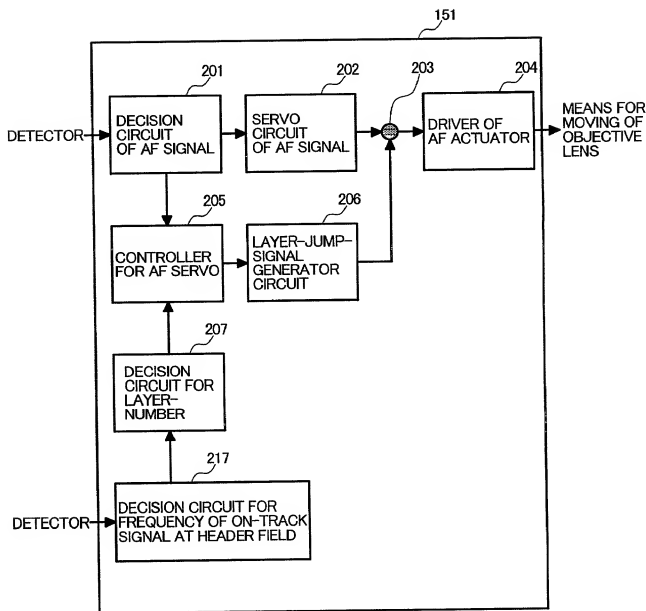


FIG.30

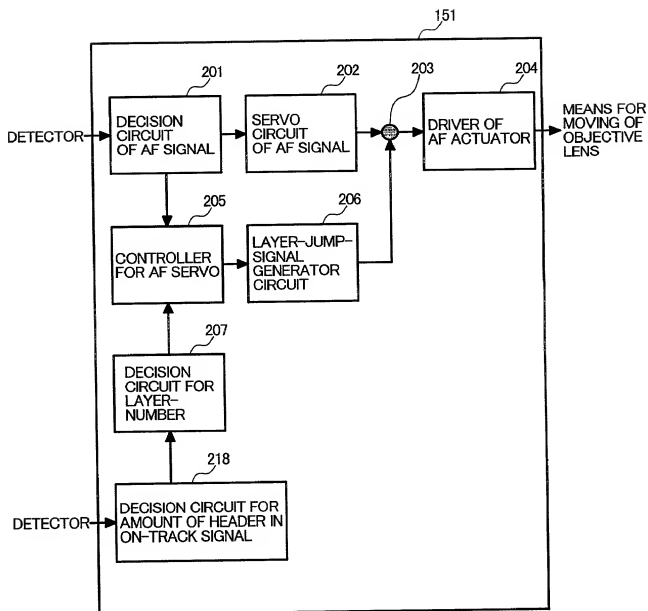


FIG.31

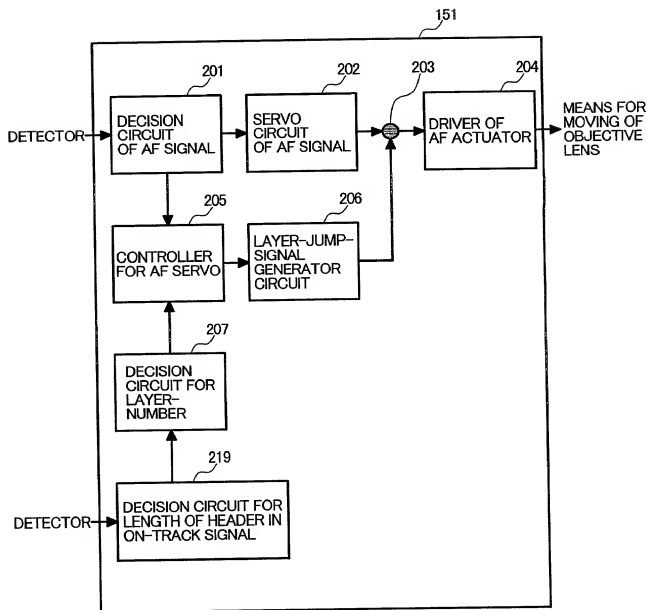


FIG.32

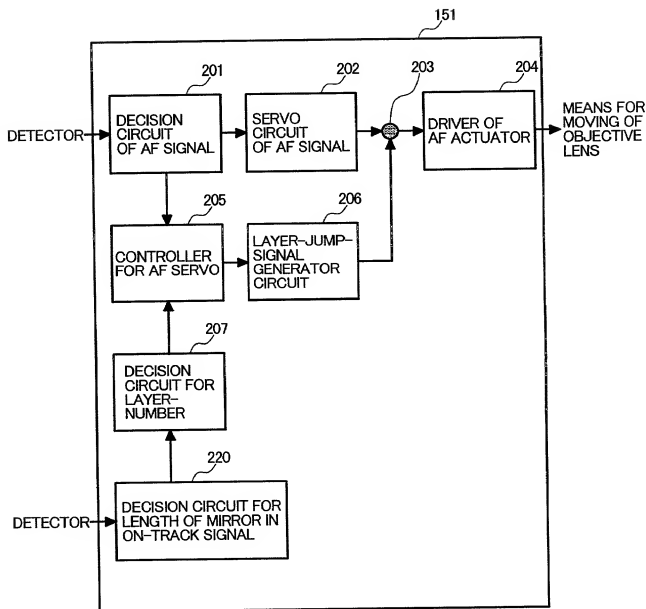


FIG.33

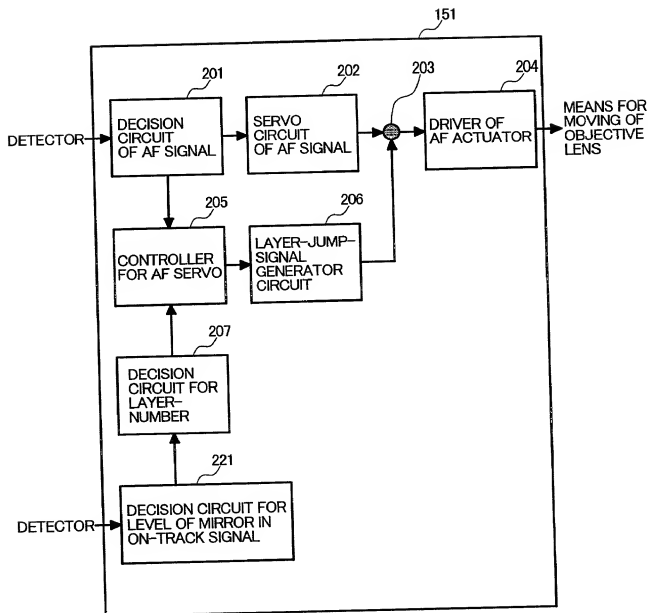


FIG.34

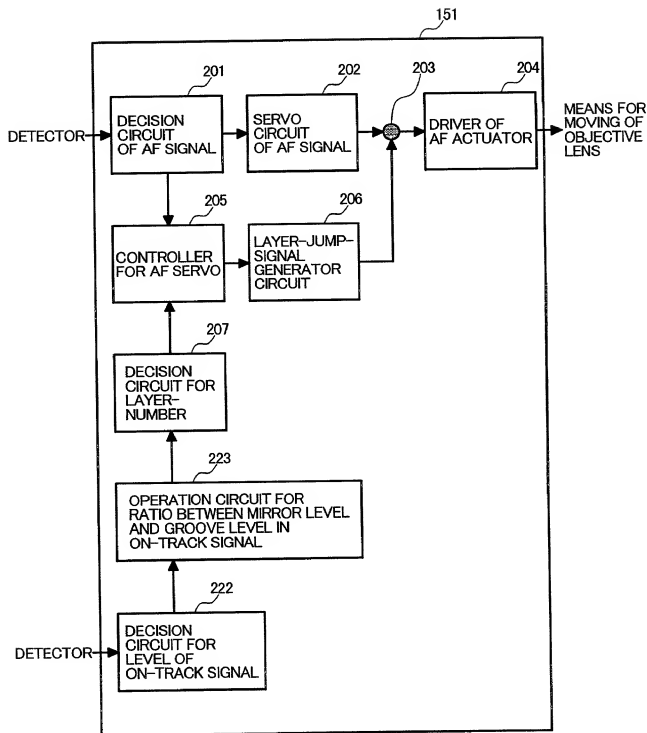


FIG.35

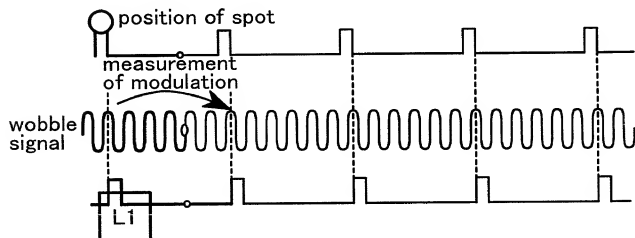
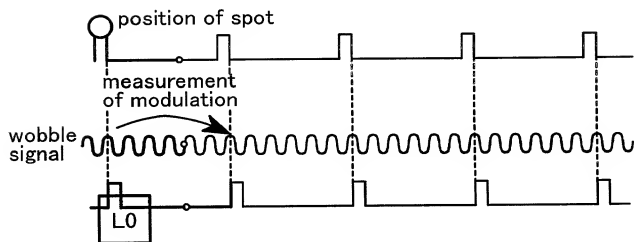
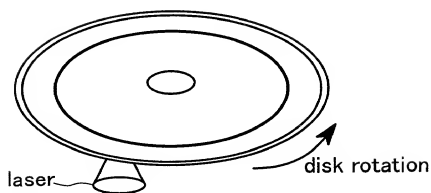


FIG.36

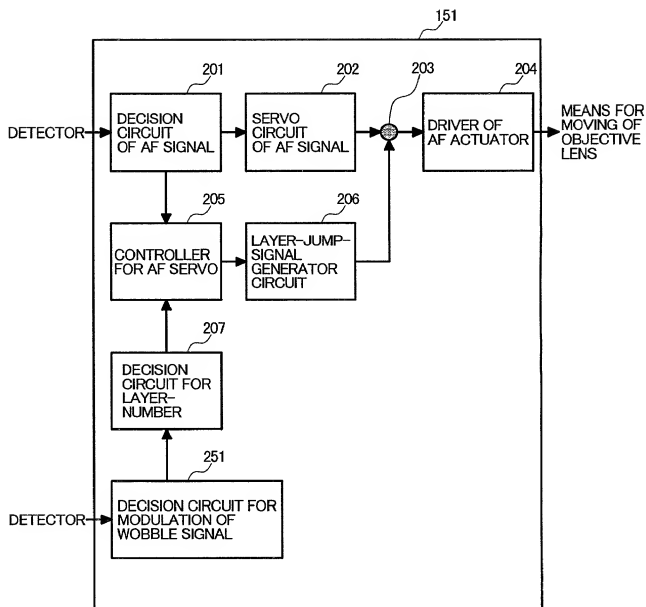


FIG.37

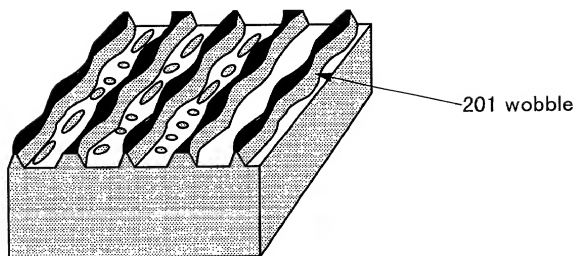


FIG.38

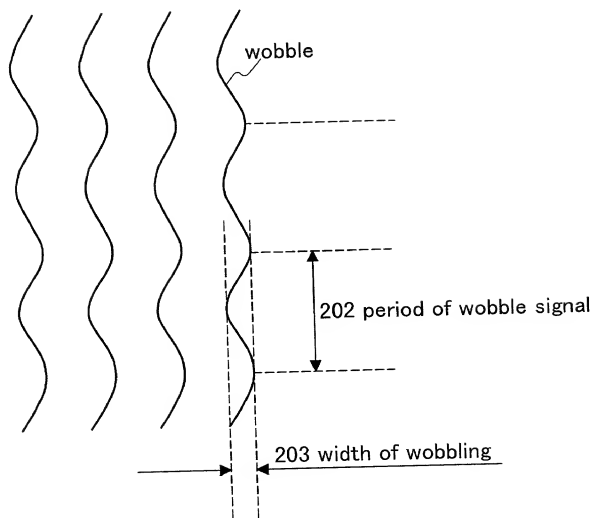


FIG.39

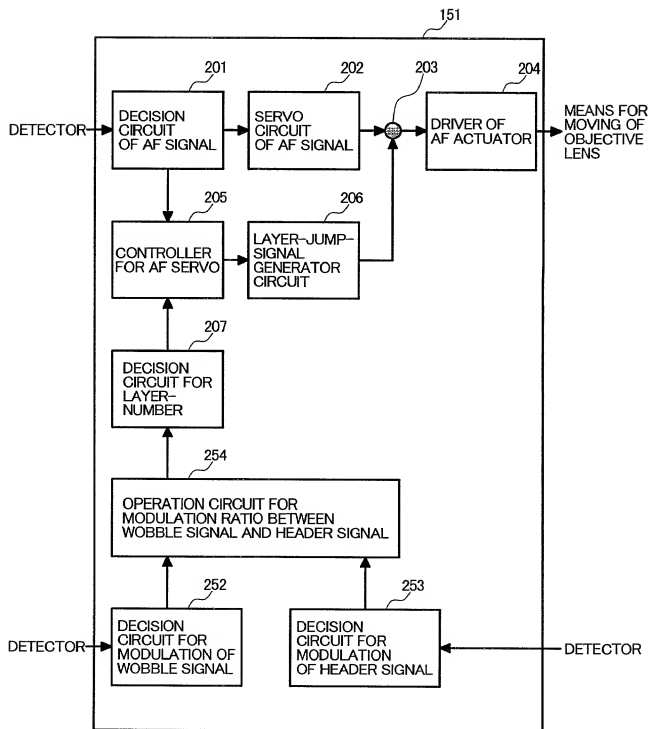


FIG.40

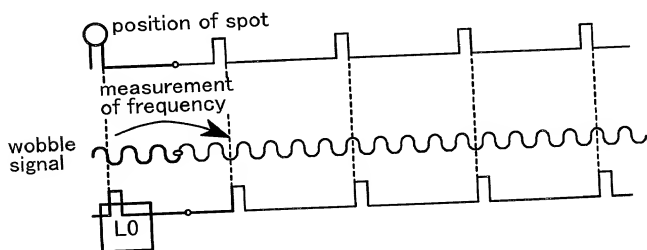
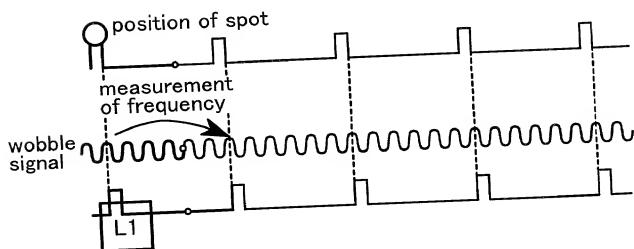
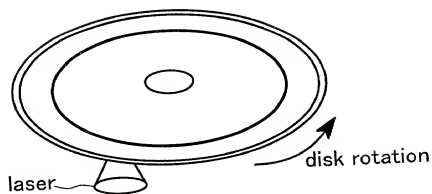


FIG.41

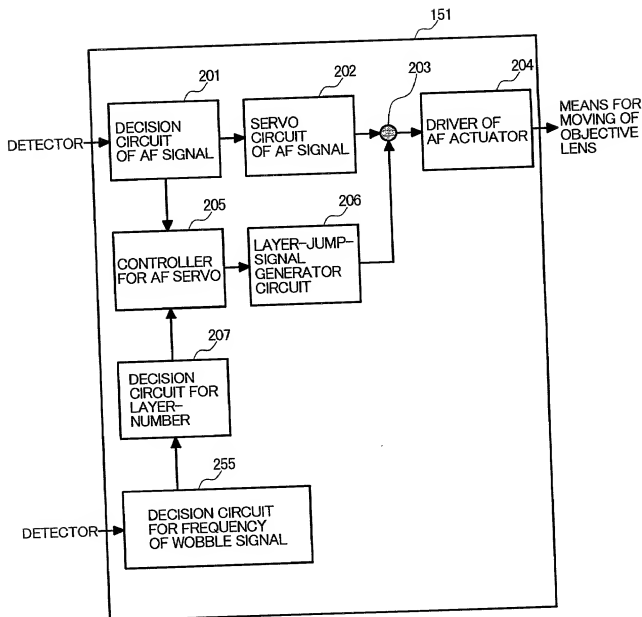


FIG.42

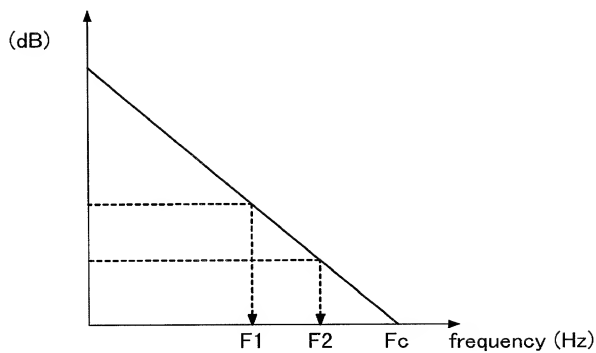


FIG.43

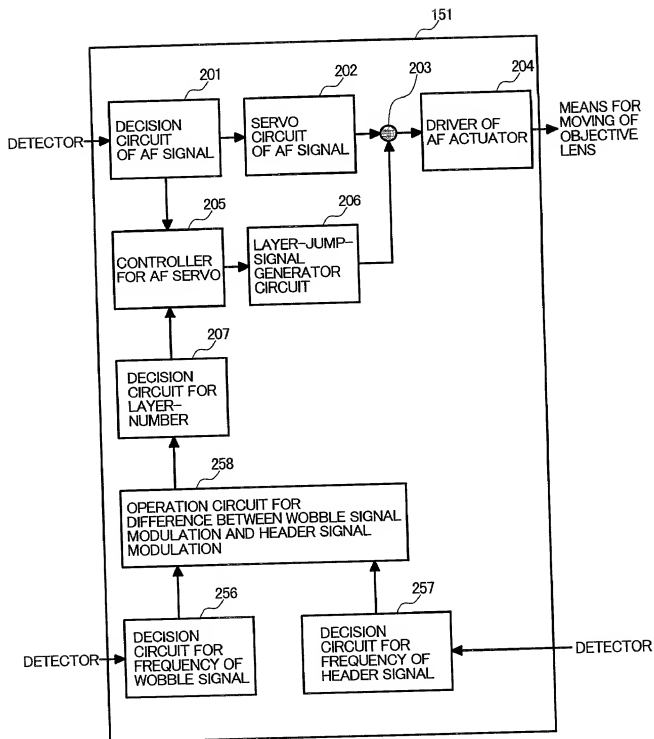


FIG.44

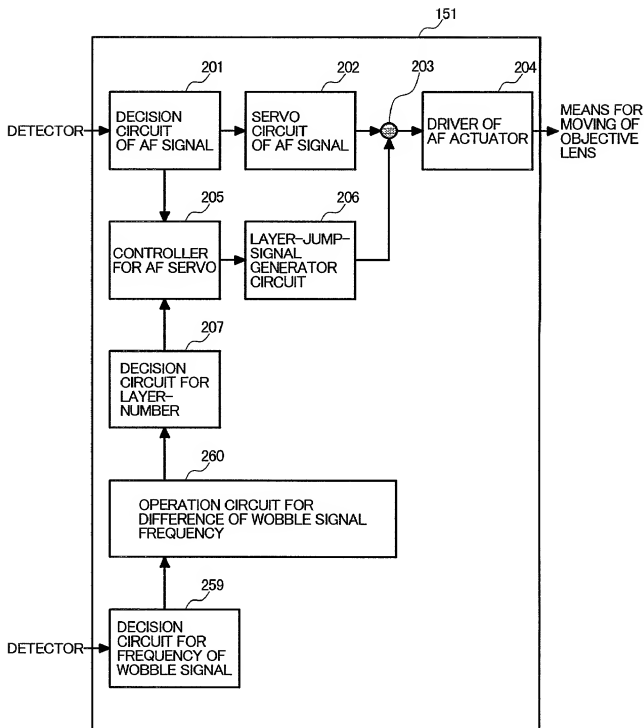


FIG.45

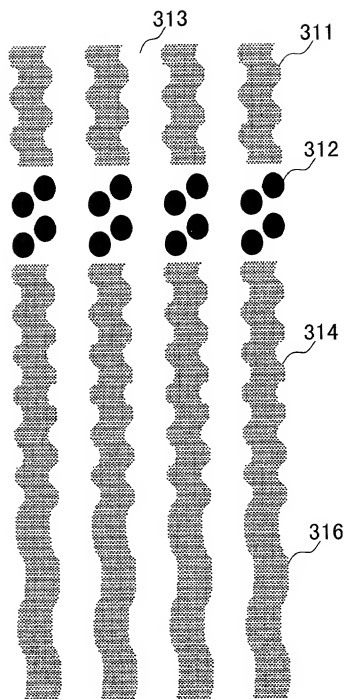


FIG.46

